

### **MEAS**

TE Internal #: GA10K3CG3

TE Internal Description: CHPG-NTC CHIP THERMISTORS

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Sensors > Temperature Sensors > NTC Thermistors Sensors & Probes > NTC Thermistors



Discrete NTC Sensor Type: NTC Thermistor

Wire Connection: Solder/Wire Bond

Resistance (at 25°C):  $10 \text{ k}\Omega$ Tolerance Resistance:  $\pm 5\%$  $\beta$ -Value(25/85): 3976 K

### **Features**

## **Product Type Features**

Discrete NTC Sensor Type	NTC Thermistor
Tolerance $\beta$ -Value	±2 %
Electrical Characteristics	
<b>β</b> -Value(25/85)	3976 K
Body Features	
Wire Connection	Solder/Wire Bond
Usage Conditions	
Resistance (at 25°C)	10 kΩ
Tolerance Resistance	± 5 %
Discrete NTC Ambient Temperature Range	-40 – 125 °C
Temperature Accuracy	± 1.2 @ 25 °C
Maximum Temperature	125 °C[257 °F]
Packaging Features	
Discrete NTC Package	Gold Chip Thermistor

# **Product Compliance**

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant	
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EU ELV Directive 2000/53/EC	Not Yet Reviewed
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

# **Compatible Parts**





# Customers Also Bought





















## **Documents**

Datasheets & Catalog Pages
Leadless\_Chip\_Gold\_10K3CG

English